

# IGBT - Ultra Field Stop

## NGTB25N120FL3WG

This Insulated Gate Bipolar Transistor (IGBT) features a robust and cost effective Ultra Field Stop Trench construction, and provides superior performance in demanding switching applications, offering both low on-state voltage and minimal switching loss. The IGBT is well suited for UPS and solar applications. Incorporated into the device is a soft and fast co-packaged free wheeling diode with a low forward voltage.

### Features

- Extremely Efficient Trench with Field Stop Technology
- $T_{Jmax} = 175^{\circ}C$
- Soft Fast Reverse Recovery Diode
- Optimized for High Speed Switching
- These are Pb-Free Devices

### Typical Applications

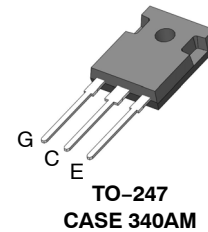
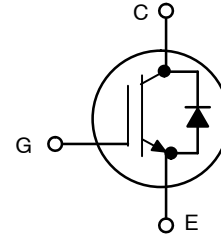
- Solar Inverter
- Uninterruptible Power Inverter Supplies (UPS)
- Welding

### ABSOLUTE MAXIMUM RATINGS

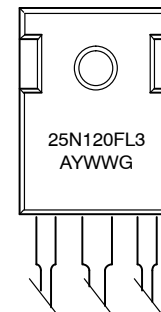
Rating	Symbol	Value	Unit
Collector-emitter Voltage	$V_{CES}$	1200	V
Collector Current @ $T_C = 25^{\circ}C$ @ $T_C = 100^{\circ}C$	$I_C$	50 25	A
Pulsed Collector Current, $T_{pulse}$ Limited by $T_{Jmax}$	$I_{CM}$	100	A
Diode Forward Current @ $T_C = 25^{\circ}C$ @ $T_C = 100^{\circ}C$	$I_F$	50 25	A
Diode Pulsed Current, $T_{pulse}$ Limited by $T_{Jmax}$	$I_{FM}$	100	A
Gate-emitter Voltage Transient Gate-emitter Voltage ( $T_{pulse} = 5 \mu s, D < 0.10$ )	$V_{GE}$	$\pm 20$ $\pm 30$	V
Power Dissipation @ $T_C = 25^{\circ}C$ @ $T_C = 100^{\circ}C$	$P_D$	349 174	W
Operating Junction Temperature Range	$T_J$	-55 to +175	$^{\circ}C$
Storage Temperature Range	$T_{stg}$	-55 to +175	$^{\circ}C$
Lead temperature for soldering, 1/8" from case for 5 seconds	$T_{SLD}$	260	$^{\circ}C$

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

25 A, 1200 V  
 $V_{CEsat} = 1.7 V$   
 $E_{off} = 0.7 mJ$



### MARKING DIAGRAM



25N120FL3 = Specific Device Code  
A = Assembly Location  
Y = Year  
WW = Work Week  
G = Pb-Free Package

### ORDERING INFORMATION

Device	Package	Shipping
NGTB25N120FL3WG	TO-247 (Pb-Free)	30 Units / Rail

# NGTB25N120FL3WG

## THERMAL CHARACTERISTICS

Rating	Symbol	Value	Unit
Thermal resistance junction-to-case, for IGBT	$R_{\theta JC}$	0.43	$^{\circ}\text{C}/\text{W}$
Thermal resistance junction-to-case, for Diode	$R_{\theta JC}$	0.78	$^{\circ}\text{C}/\text{W}$
Thermal resistance junction-to-ambient	$R_{\theta JA}$	40	$^{\circ}\text{C}/\text{W}$

## ELECTRICAL CHARACTERISTICS ( $T_J = 25^{\circ}\text{C}$ unless otherwise specified)

Parameter	Test Conditions	Symbol	Min	Typ	Max	Unit
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### STATIC CHARACTERISTIC

Collector-emitter breakdown voltage, gate-emitter short-circuited	$V_{GE} = 0\text{ V}, I_C = 500\ \mu\text{A}$	$V_{(BR)CES}$	1200	-	-	V
Collector-emitter saturation voltage	$V_{GE} = 15\text{ V}, I_C = 25\text{ A}$ $V_{GE} = 15\text{ V}, I_C = 25\text{ A}, T_J = 175^{\circ}\text{C}$	$V_{CEsat}$	-	1.70 2.20	1.95 -	V
Gate-emitter threshold voltage	$V_{GE} = V_{CE}, I_C = 400\ \mu\text{A}$	$V_{GE(th)}$	4.5	5.5	6.5	V
Collector-emitter cut-off current, gate-emitter short-circuited	$V_{GE} = 0\text{ V}, V_{CE} = 1200\text{ V}$ $V_{GE} = 0\text{ V}, V_{CE} = 1200\text{ V}, T_J = 175^{\circ}\text{C}$	$I_{CES}$	-	-	0.1 2	mA
Gate leakage current, collector-emitter short-circuited	$V_{GE} = 20\text{ V}, V_{CE} = 0\text{ V}$	$I_{GES}$	-	-	200	nA

### DYNAMIC CHARACTERISTIC

Input capacitance	$V_{CE} = 20\text{ V}, V_{GE} = 0\text{ V}, f = 1\text{ MHz}$	$C_{ies}$	-	3085	-	pF
Output capacitance		$C_{oes}$	-	94	-	
Reverse transfer capacitance		$C_{res}$	-	52	-	
Gate charge total	$V_{CE} = 600\text{ V}, I_C = 25\text{ A}, V_{GE} = 15\text{ V}$	$Q_g$	-	136	-	nC
Gate to emitter charge		$Q_{ge}$	-	29	-	
Gate to collector charge		$Q_{gc}$	-	67	-	

### SWITCHING CHARACTERISTIC, INDUCTIVE LOAD

Turn-on delay time	$T_J = 25^{\circ}\text{C}$ $V_{CC} = 600\text{ V}, I_C = 25\text{ A}$ $R_g = 10\ \Omega$ $V_{GE} = 15\text{ V}$	$t_{d(on)}$	-	15	-	ns	
Rise time		$t_r$	-	21	-		
Turn-off delay time		$t_{d(off)}$	-	109	-		
Fall time			$t_f$	-	131	-	mJ
Turn-on switching loss		$E_{on}$	-	1.0	-		
Turn-off switching loss		$E_{off}$	-	0.7	-		
Total switching loss		$E_{ts}$	-	1.7	-		
Turn-on delay time	$T_J = 150^{\circ}\text{C}$ $V_{CC} = 600\text{ V}, I_C = 25\text{ A}$ $R_g = 10\ \Omega$ $V_{GE} = 15\text{ V}$	$t_{d(on)}$	-	15	-	ns	
Rise time		$t_r$	-	21	-		
Turn-off delay time		$t_{d(off)}$	-	113	-		
Fall time			$t_f$	-	169	-	mJ
Turn-on switching loss		$E_{on}$	-	1.45	-		
Turn-off switching loss		$E_{off}$	-	0.95	-		
Total switching loss		$E_{ts}$	-	2.4	-		

### DIODE CHARACTERISTICS

Forward voltage	$V_{GE} = 0\text{ V}, I_F = 25\text{ A}$ $V_{GE} = 0\text{ V}, I_F = 25\text{ A}, T_J = 175^{\circ}\text{C}$	$V_F$	-	3.0 2.8	3.4 -	V
Reverse recovery time	$T_J = 25^{\circ}\text{C}$ $I_F = 25\text{ A}, V_R = 600\text{ V}$ $di_F/dt = 500\text{ A}/\mu\text{s}$	$t_{rr}$	-	90	-	ns
Reverse recovery charge		$Q_{rr}$	-	0.62	-	$\mu\text{C}$
Reverse recovery current		$I_{rrm}$	-	12	-	A
Diode peak rate of fall of reverse recovery current during $t_b$		$di_{rrm}/dt$	-	-256	-	$\text{A}/\mu\text{s}$

# NGTB25N120FL3WG

## ELECTRICAL CHARACTERISTICS ( $T_J = 25^\circ\text{C}$ unless otherwise specified)

Parameter	Test Conditions	Symbol	Min	Typ	Max	Unit
<b>DIODE CHARACTERISTICS</b>						
Reverse recovery time	$T_J = 125^\circ\text{C}$ $I_F = 25\text{ A}$ , $V_R = 600\text{ V}$ $di_F/dt = 500\text{ A}/\mu\text{s}$	$t_{rr}$	–	114	–	ns
Reverse recovery charge		$Q_{rr}$	–	1.17	–	$\mu\text{C}$
Reverse recovery current		$I_{rrm}$	–	17	–	A
Diode peak rate of fall of reverse recovery current during $t_b$		$dI_{rrm}/dt$	–	–296	–	$\text{A}/\mu\text{s}$

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

# NGTB25N120FL3WG

## TYPICAL CHARACTERISTICS

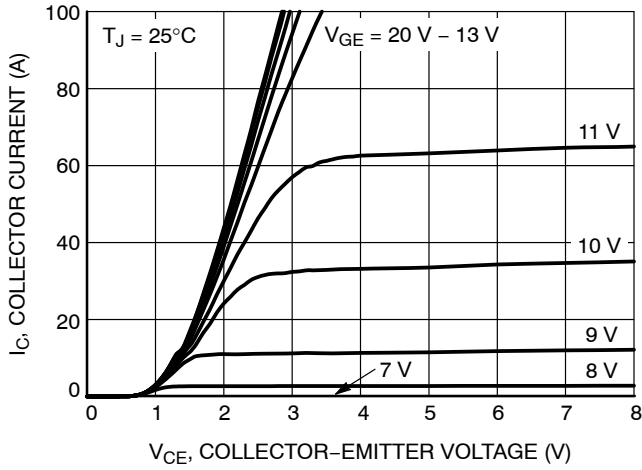


Figure 1. Output Characteristics

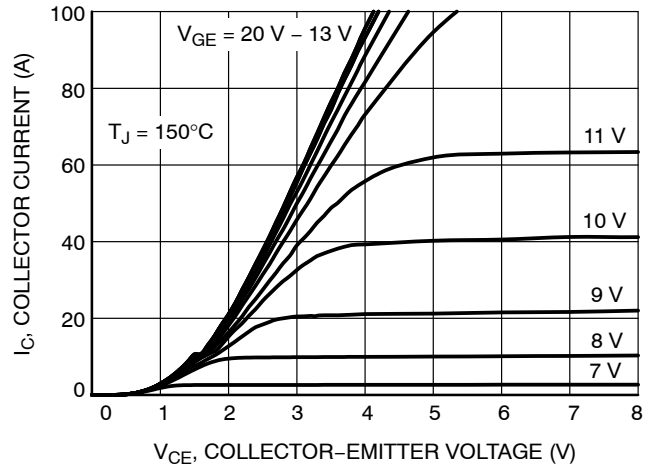


Figure 2. Output Characteristics

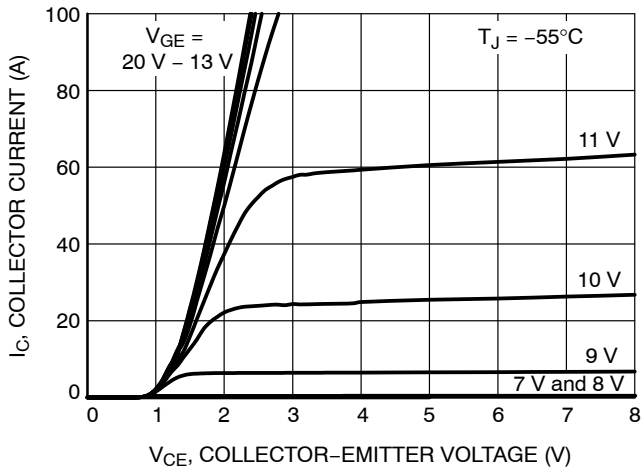


Figure 3. Output Characteristics

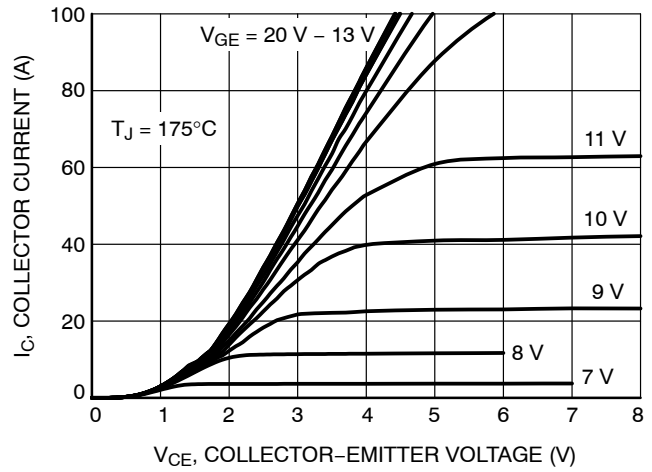


Figure 4. Output Characteristics

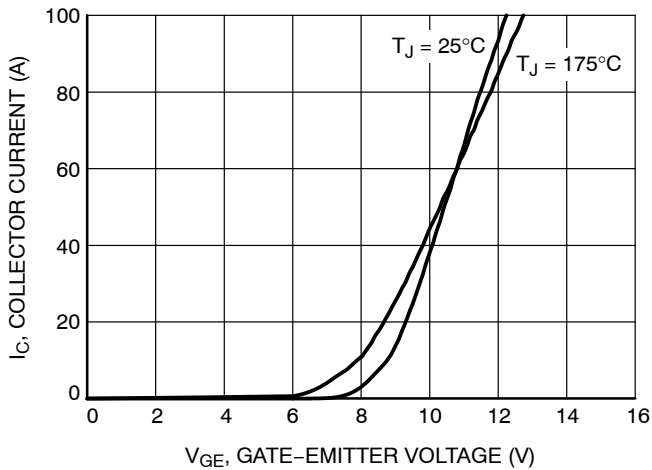


Figure 5. Typical Transfer Characteristics

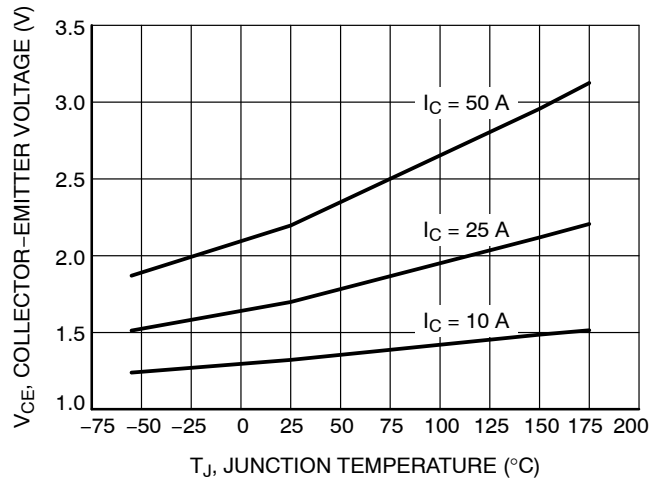


Figure 6.  $V_{CE(sat)}$  vs.  $T_J$

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## TYPICAL CHARACTERISTICS

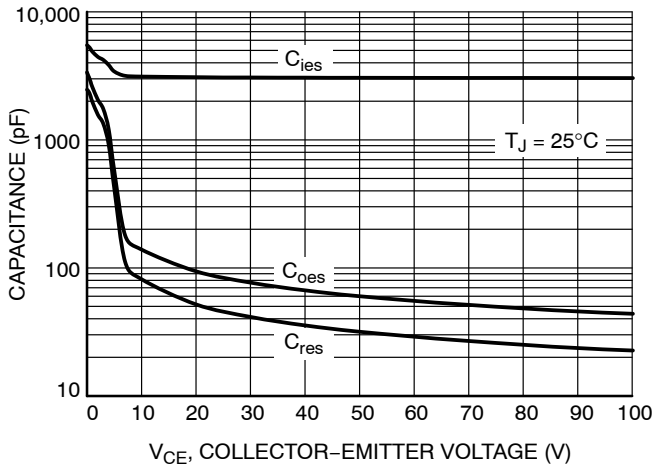


Figure 7. Typical Capacitance

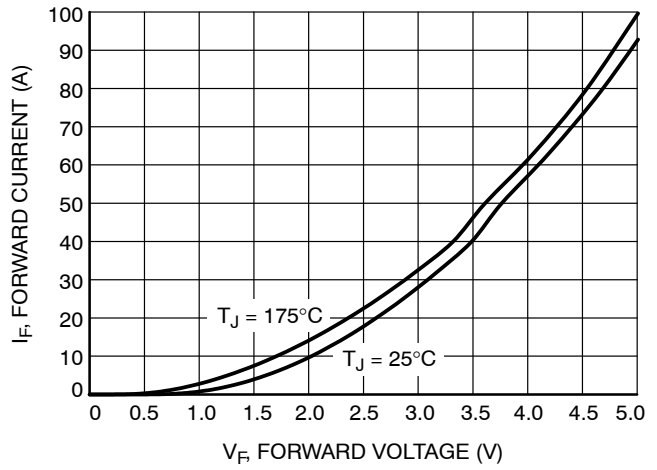


Figure 8. Diode Forward Characteristics

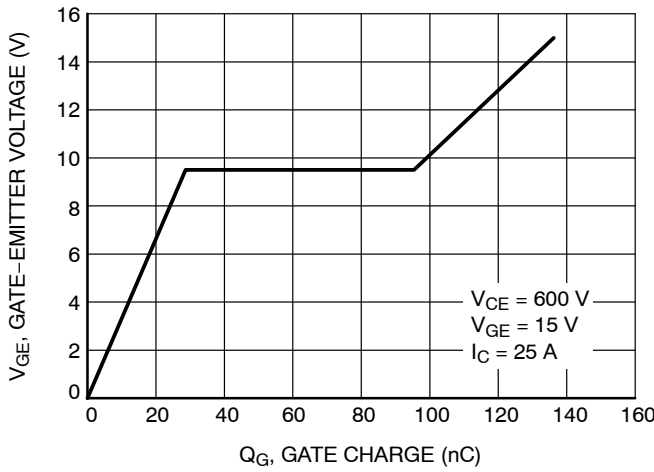


Figure 9. Typical Gate Charge

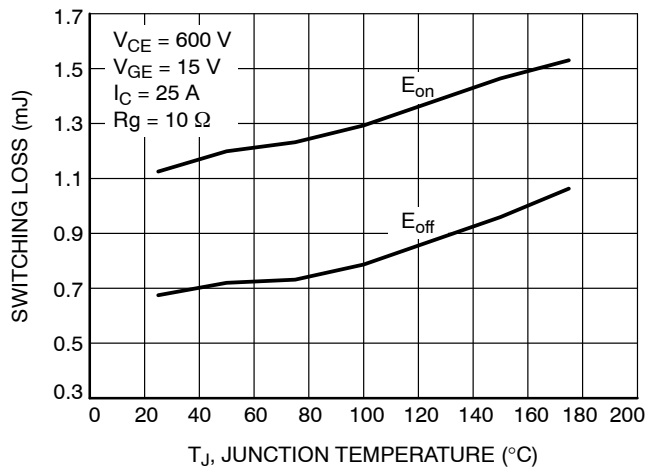


Figure 10. Switching Loss vs. Temperature

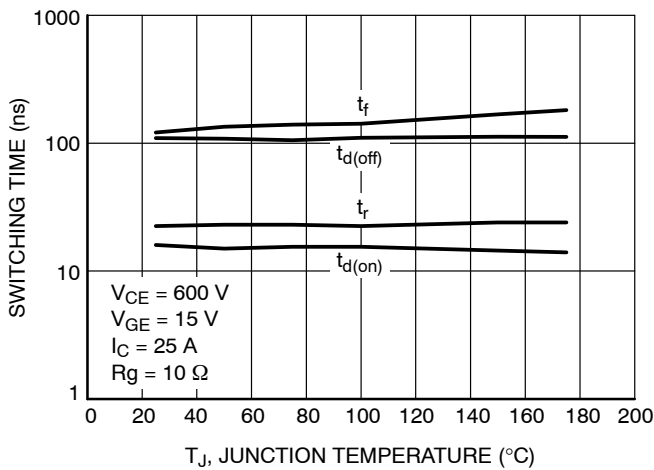


Figure 11. Switching Time vs. Temperature

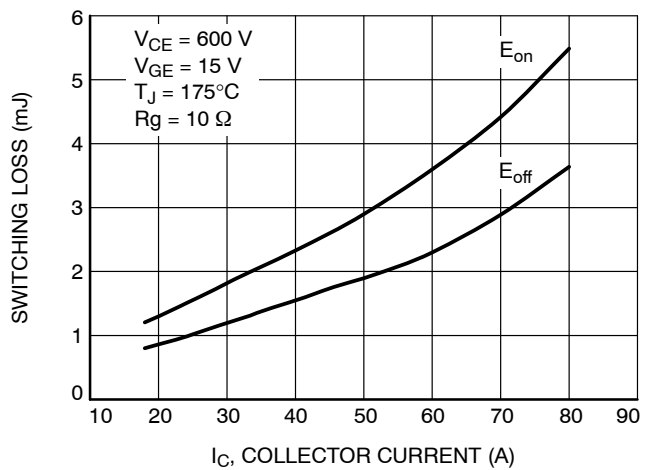


Figure 12. Switching Loss vs. I\_C

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## TYPICAL CHARACTERISTICS

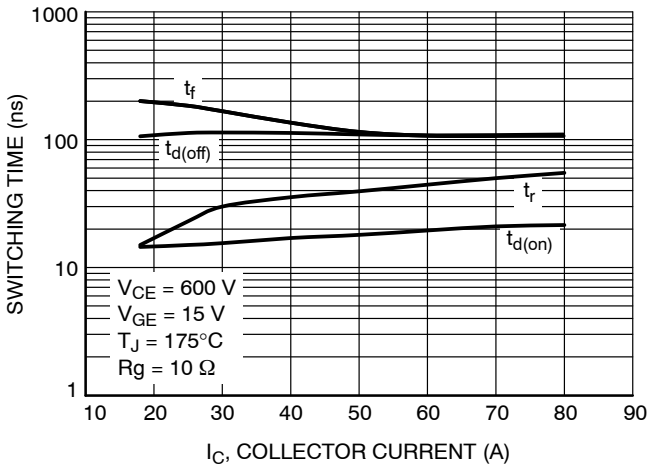


Figure 13. Switching Time vs.  $I_C$

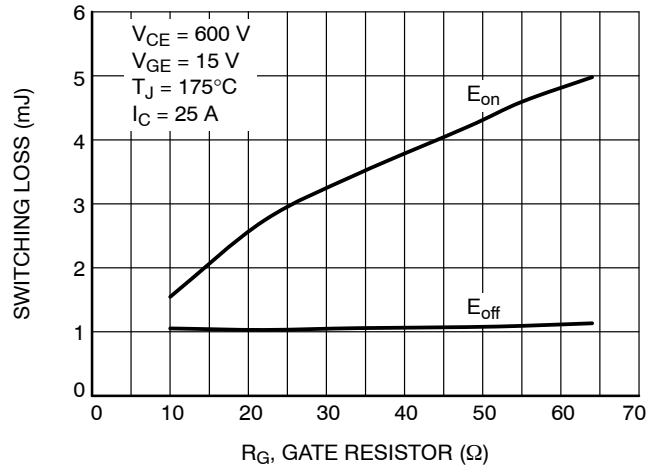


Figure 14. Switching Loss vs.  $R_G$

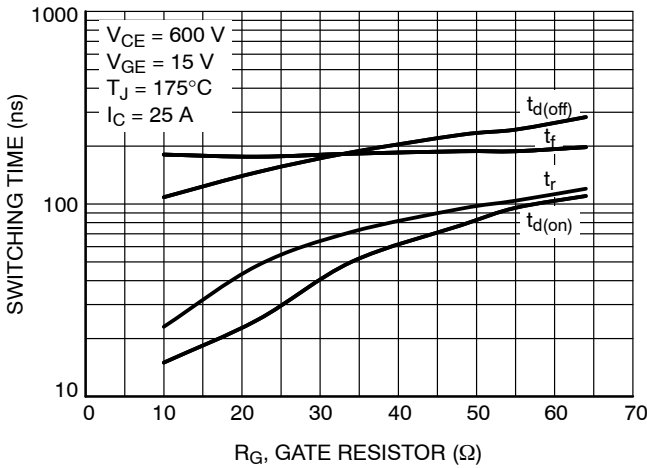


Figure 15. Switching Time vs.  $R_G$

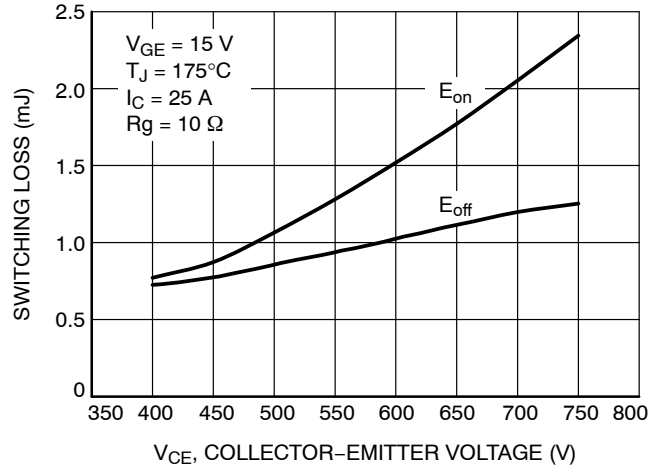


Figure 16. Switching Loss vs.  $V_{CE}$

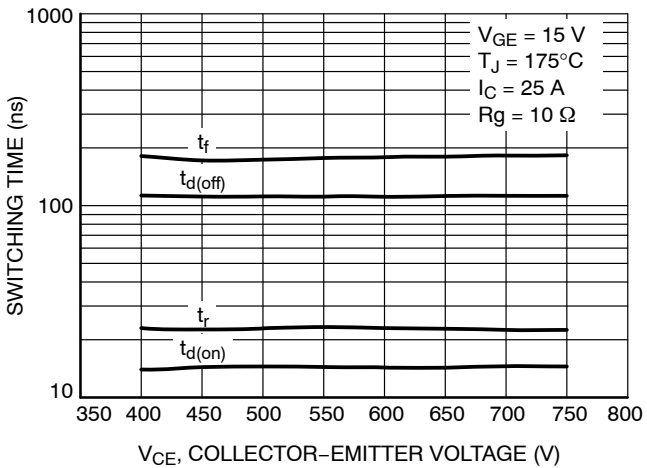


Figure 17. Switching Time vs.  $V_{CE}$

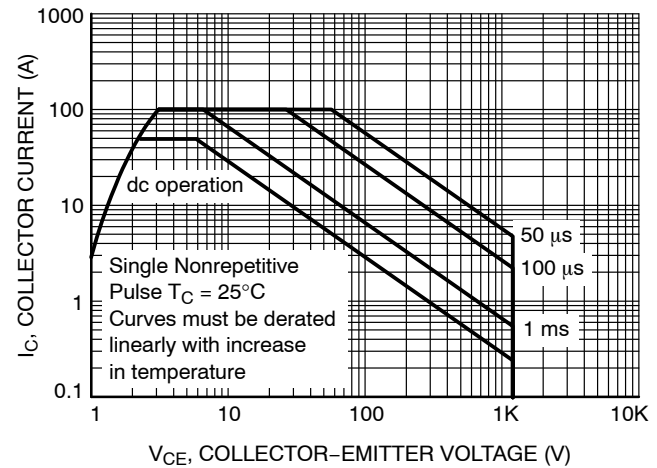


Figure 18. Safe Operating Area

# NGTB25N120FL3WG

## TYPICAL CHARACTERISTICS

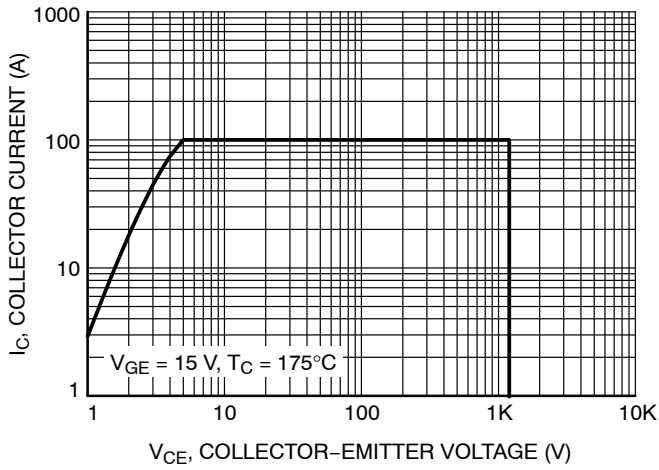


Figure 19. Reverse Bias Safe Operating Area

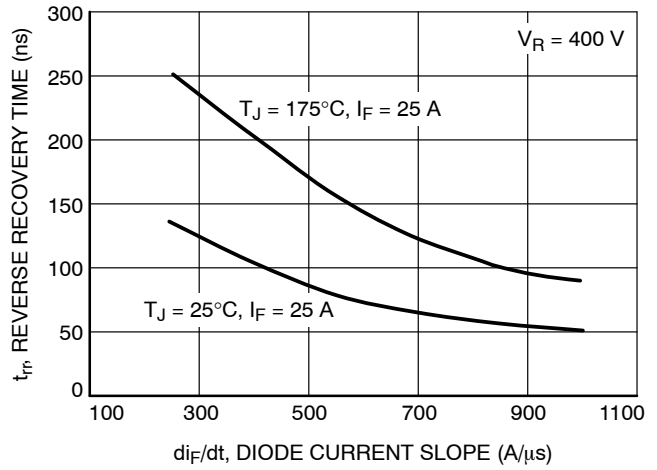


Figure 20.  $t_{rr}$  vs.  $di_F/dt$

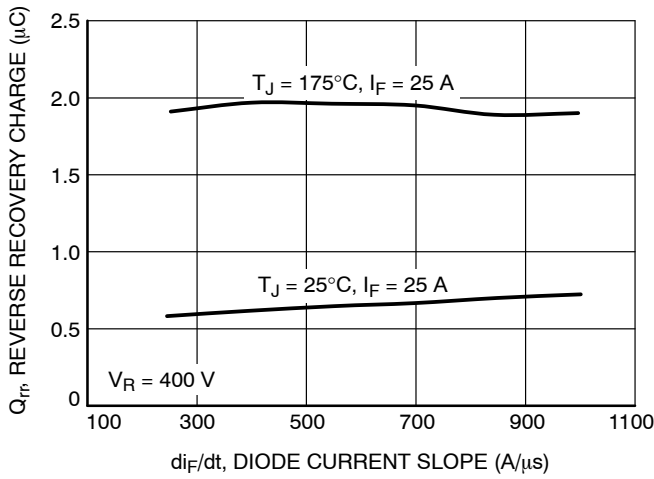


Figure 21.  $Q_{rr}$  vs.  $di_F/dt$

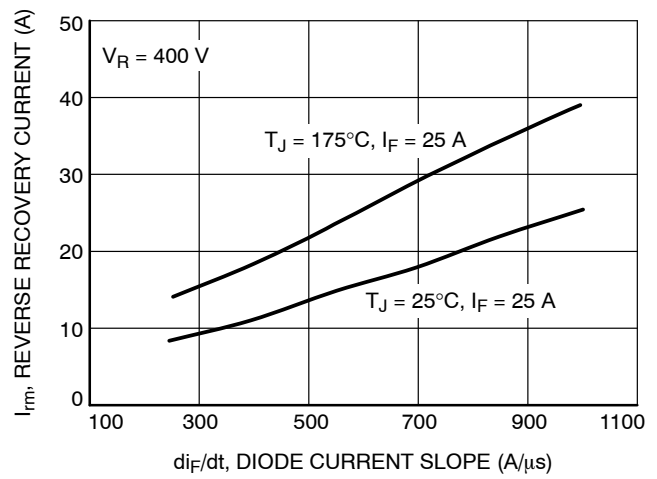


Figure 22.  $I_{rrm}$  vs.  $di_F/dt$

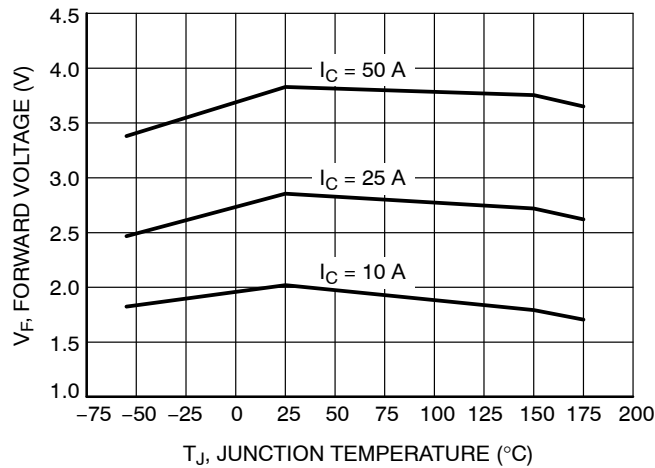


Figure 23.  $V_F$  vs.  $T_J$

# NGTB25N120FL3WG

## TYPICAL CHARACTERISTICS

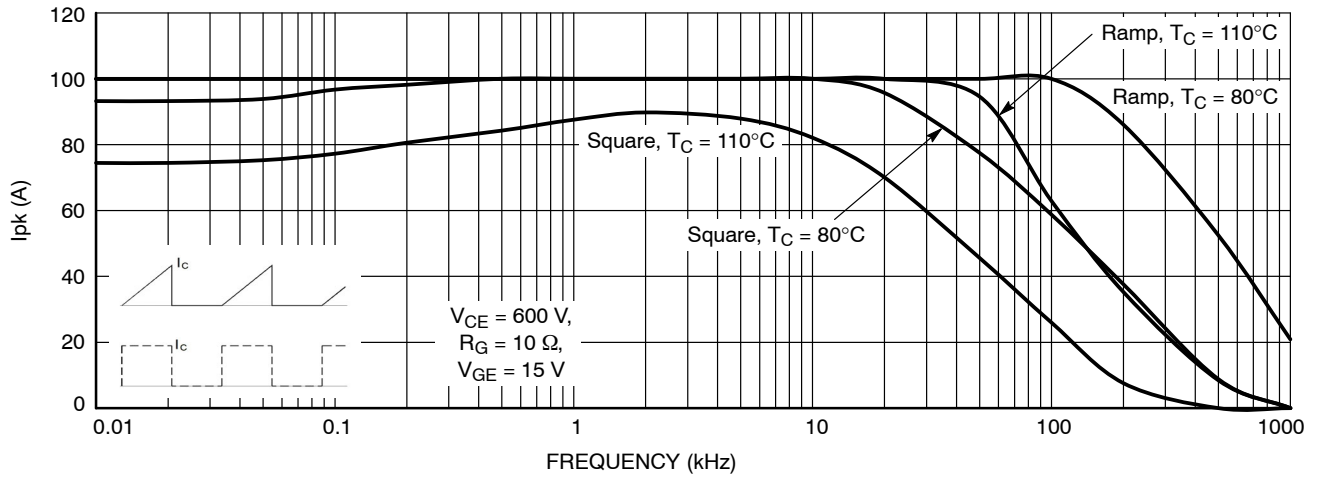


Figure 24. Collector Current vs. Switching Frequency

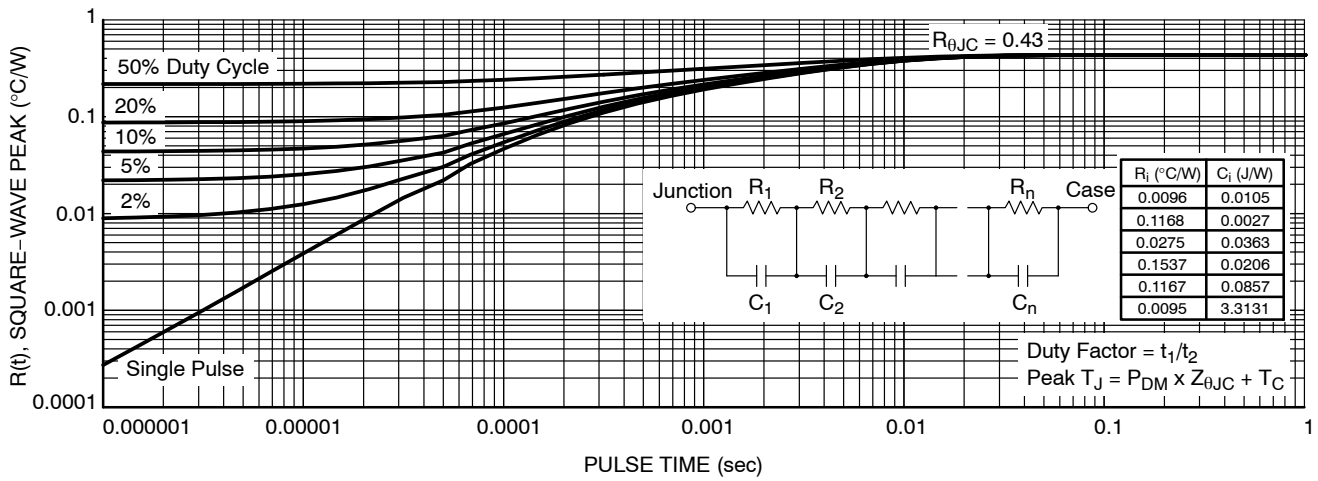


Figure 25. IGBT Transient Thermal Impedance

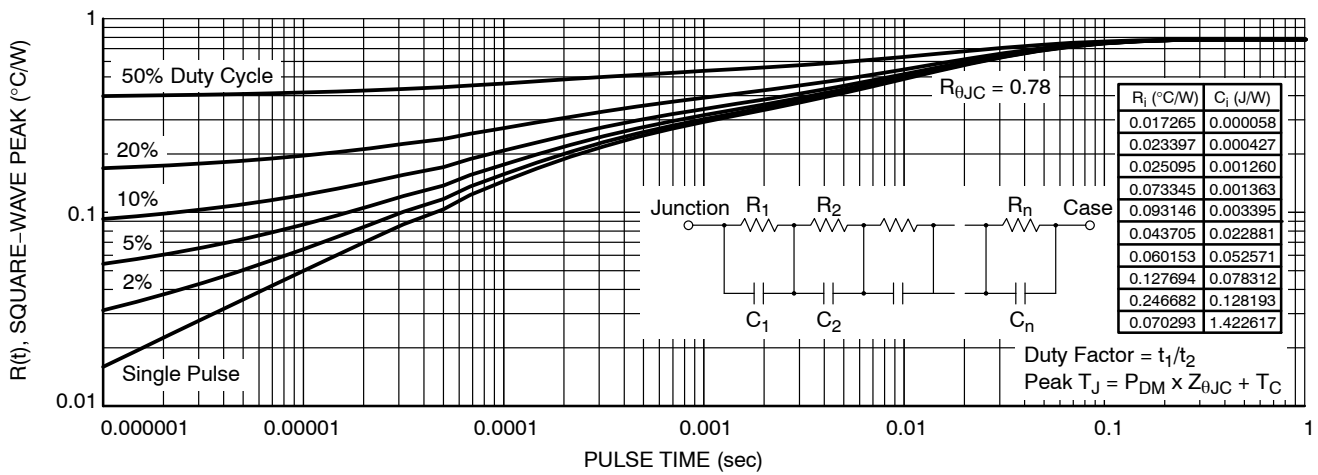


Figure 26. Diode Transient Thermal Impedance



NGTB25N120FL3WG

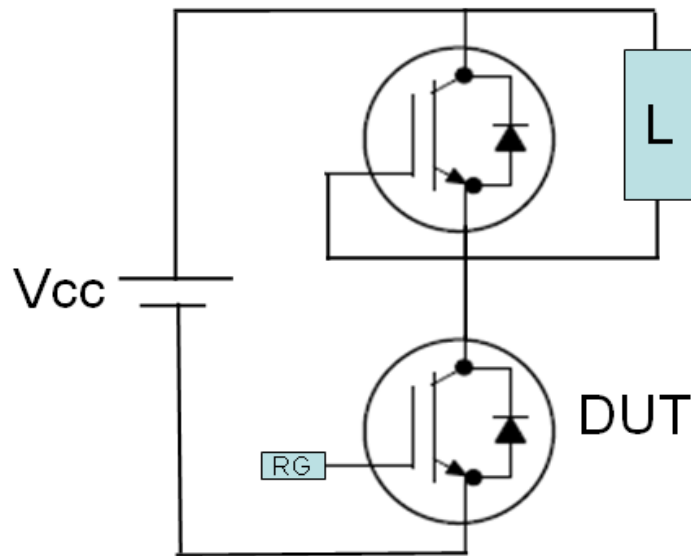


Figure 27. Test Circuit for Switching Characteristics

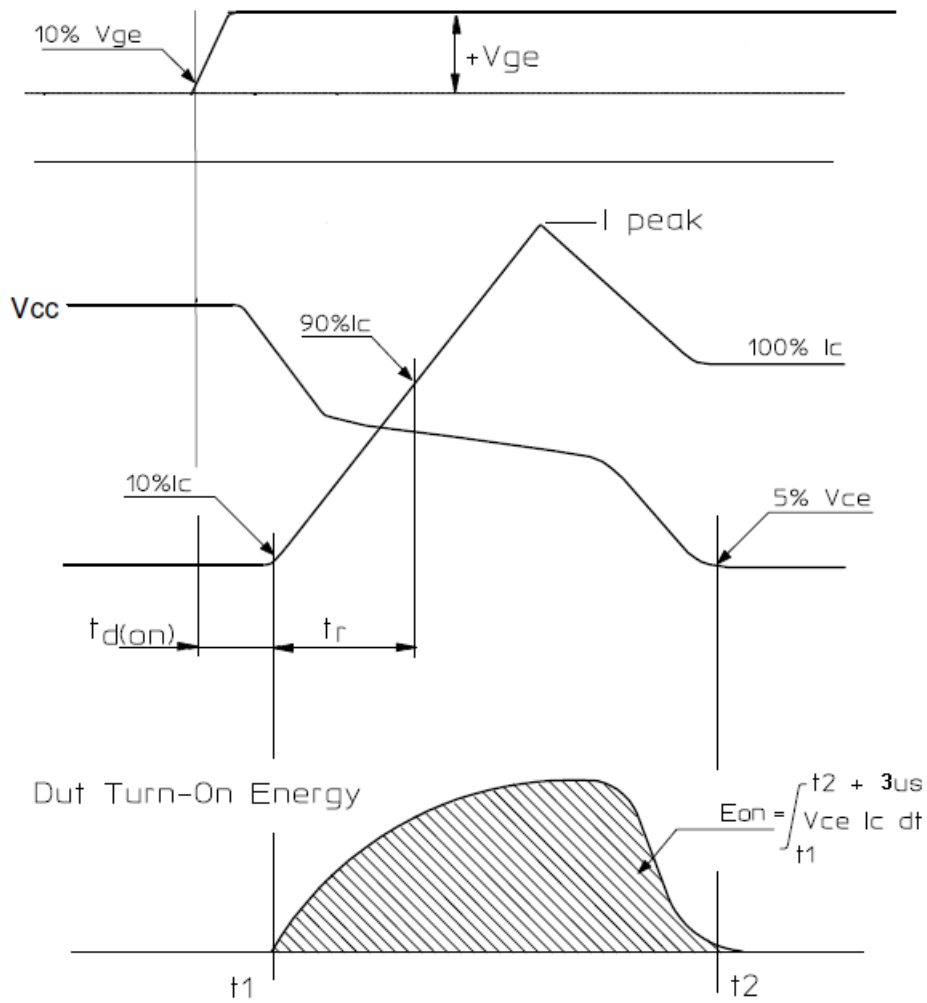


Figure 28. Definition of Turn On Waveform

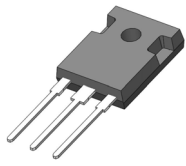
# NGTB25N120FL3WG



Figure 29. Definition of Turn Off Waveform

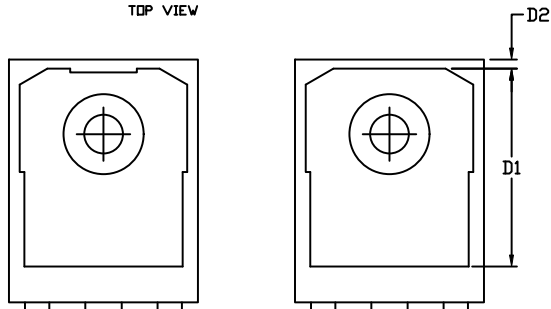
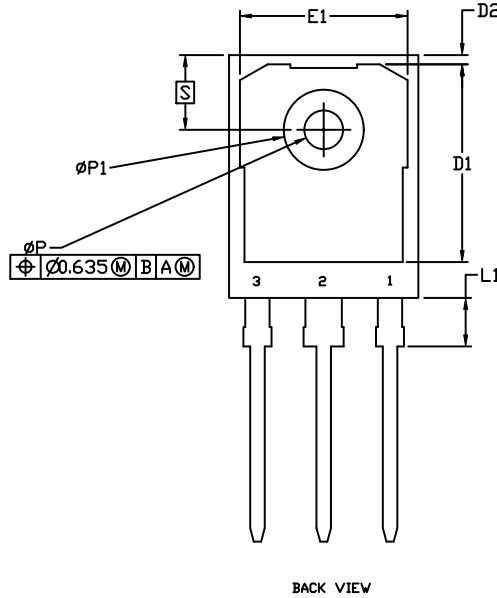
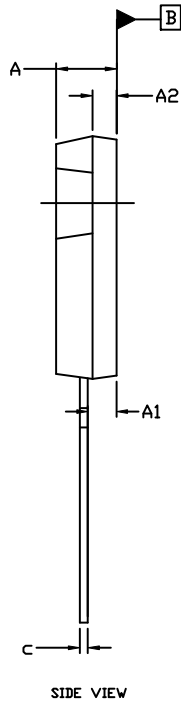
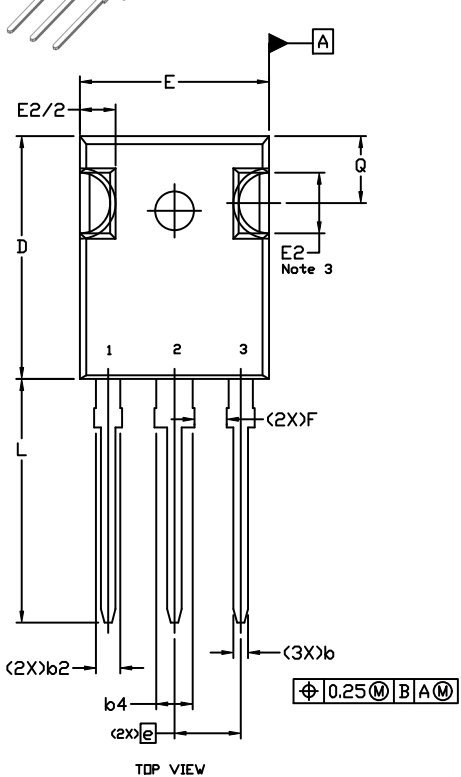
# MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

ON Semiconductor®



TO-247  
CASE 340AM  
ISSUE C

DATE 07 SEP 2021



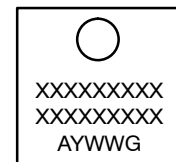
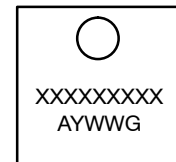
NOTE 4 HEATSINK SHAPES

NOTES:

1. DIMENSIONING AND TOLERANCE AS PER ASME Y14.5M, 2009.
2. ALL DIMENSION ARE IN MILLIMETERS.
3. SLOT REQUIRED, NOTCH MAY BE ROUNDED.
4. OPTIONAL BACK SIDE HEATSINK SHAPE.
5. DIMENSIONS ARE EXCLUSIVE OF BURRS AND MOLD FLASH. DIMENSIONS D AND E ARE MEASURED AT THE OUTERMOST EXTREME OF THE PLASTIC BODY.
6. DIMENSIONS A1 TO BE MEASURED IN THE REGION DEFINED BY L1.
7. LEAD FINISH IS UNCONTROLLED IN THE REGION DEFINED BY L1.

DIM	MILLIMETERS		
	MIN	NOM	MAX
A	4.70	5.00	5.30
A1	2.20	2.40	2.60
A2	1.80	2.00	2.20
b	1.07	1.20	1.33
b2	1.65	2.12	2.35
b4	2.60	3.12	3.40
c	0.45	0.60	0.75
D	20.80	21.00	21.34
D1	16.30	---	---
D2	0.75	---	---
E	15.50	16.00	16.25
E1	13.80	---	---
E2	4.32	4.90	5.49
e	5.45 BSC		
F	2.655	---	---
L	19.80	20.00	20.80
L1	3.81	4.20	4.35
P	3.55	3.60	3.65
P1	6.60	---	---
Q	5.40	6.00	6.20
S	6.15 BSC		

GENERIC MARKING DIAGRAMS\*



XXXX = Specific Device Code  
A = Assembly Location  
Y = Year  
WW = Work Week  
G = Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

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